

ELECTRICAL:

CONTACT RESISTANCE:

20 milliohms MAX at 1 amp. DC.

INSULATION RESISTANCE:

5,000 megohms MIN at 500VDC.

DIELECTRIC WITHSTANDING VOLTAGE:

800VAC/RMS at 60Hz for one minute.

VOLTAGE RATING:

800VAC/RMS at 60Hz.

CURRENT RATING:

1.0 amps. per contact.

MECHANICAL:

INSERTION FORCE: 230 grams MAX. per contact pair.

WITHDRAWAL FORCE: 15 grams MAX. per contact pair.

CONTACT RETENTION: 680 grams MAX. per contact pair.

DURABILITY:

200 mating/unmating cycles MIN. at flash gold over 0.76 micrometers

MIN. of palladium/nickel

50 mating/unmating cycles MIN. at flash gold plating;

100 mating/unmating cycles MIN. at 0.38 micrometers MIN. gold plating;

200 mating/unmating cycles MIN. at 0.38 micrometers MIN. gold plating.

ENVIRONMENTAL:

OPERATING TEMPERATURE: -55°C to +105°C

HUMIDITY: per MIL-STD-1334A, method 1002.1, test condition B

THERMAL SHOCK: per MIL-STD-1334A, method 1003.1, test condition A

VIBRATION: per MIL-STD-1334A, method 2005.1, test condition II

MECHANICAL SHOCK: per MIL-STD-1334A, method 2004.1, test condition C

SALT SPRAY: 24 hours per MIL-STD-1334A, method 1001.1, test condition

MATERIAL:

INSULATOR:

glass-filled thermoplastic (PPS/NYLON-66/PBT),UL-94V-0 rated.

color-white, for PCI connector

CONTACT:

phosphor bronze, per ASTM-B103

Mating area - selective gold over 1.27 micrometers MIN. of nickel,

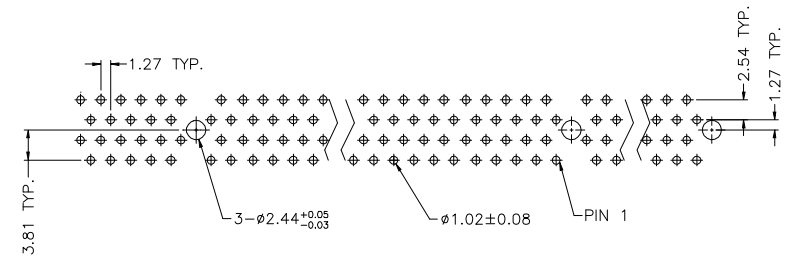
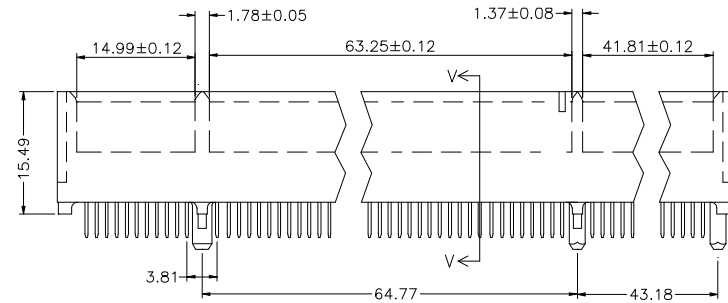
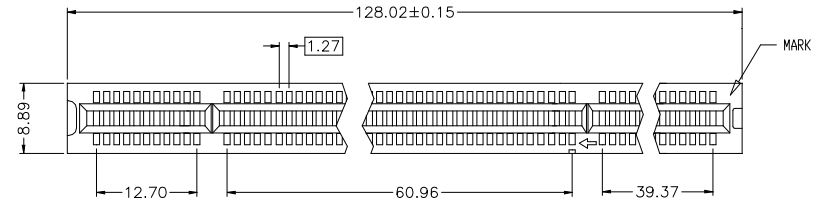
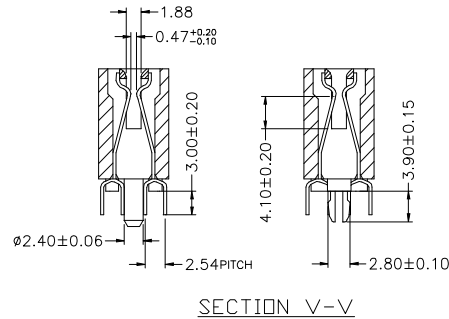
or flash gold over 0.76 micrometers MIN. of nickel

Termination area - 2.54 micrometers MIN. of tin/lead over

1.27 micrometers MIN. of nickel

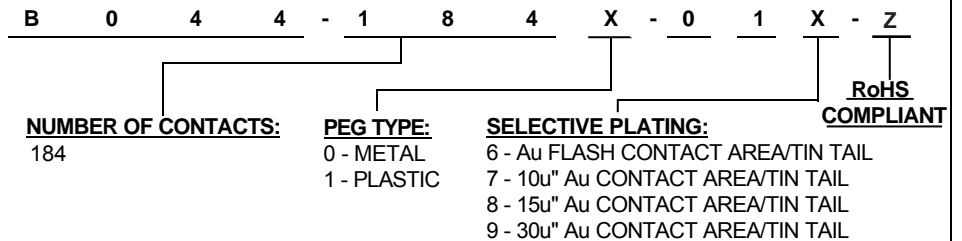
CLIPS (Boardlock):

stainless



P. C. B. HOLE LAYOUT

HOW TO ORDER:



Rev		Apv.	Date
0	Issued	A.M.	05/30/01
A	Revised For RoHS Complianace	A.M.	06/30/05

SMP TECHNOLOGY, INC.

SCALE	MAT'L	FINISH	UNIT: mm
TOL. DEC.	.X +/- 0.25	.XX +/- 0.15	.XXX +/- 0.08
		ANGLE +/- 0.50°	

PCI Connector, 184 Positions, 3.3 Volt
P/N: B044-184X-01X
Pg: 1